

Title (en)

DIE AND METHOD OF MANUFACTURING SAME

Title (de)

CHIP UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

MATRICE ET PROCÉDÉ DE FABRICATION DE CELLE-CI

Publication

**EP 2418305 B1 20160928 (EN)**

Application

**EP 10761432 A 20100406**

Priority

- JP 2010002518 W 20100406
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Abstract (en)

[origin: EP2418305A1] A mold of the present invention includes: a base 12 made of glass or plastic; an inorganic underlayer 14 provided on a surface of the base 12; a buffer layer 16 provided on the inorganic underlayer 14, the buffer layer 16 containing aluminum; an aluminum layer 18a provided on a surface of the buffer layer 16; and a porous alumina layer 20 provided on a surface of the aluminum layer 18a. The porous alumina layer 20 has a plurality of recessed portions 22 whose two-dimensional size viewed in a direction normal to the surface is not less than 10 nm and less than 500 nm. The mold of the present invention has excellent adhesion between the aluminum layer and the base.

IPC 8 full level

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CPC (source: EP US)

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Cited by

EP2554717A4; EP2426237A4; US8545708B2; US9556532B2

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DOCDB simple family (publication)

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